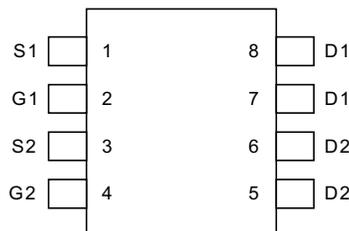


Dual P-Channel Enhancement Mode MOSFET

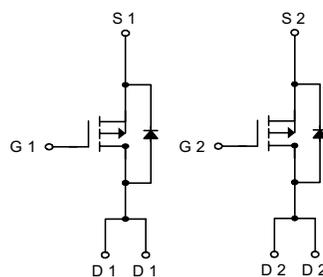
### Features

- -30V/-4.9A,  $R_{DS(ON)} = 53m\Omega(\text{typ.}) @ V_{GS} = -10V$   
 $R_{DS(ON)} = 80m\Omega(\text{typ.}) @ V_{GS} = -4.5V$
- Super High Density Cell Design
- Reliable and Rugged
- SO-8 Package

### Pin Description



SO-8



P-Channel MOSFET

### Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems

### Ordering and Marking Information

<p>APM4953 □□-□□</p> <p>Handling Code</p> <p>Temp. Range</p> <p>Package Code</p>	<p>Package Code K : SO-8</p> <p>Operation Junction Temp. Range C : -55 to 150°C</p> <p>Handling Code TU : Tube TR : Tape &amp; Reel</p>
<p>APM4953 K : <span style="border: 1px solid black; padding: 2px;">APM4953 XXXXX</span></p>	<p>XXXXX - Date Code</p>

### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Unit
$V_{DSS}$	Drain-Source Voltage	-30	V
$V_{GSS}$	Gate-Source Voltage	$\pm 25$	
$I_D^*$	Maximum Drain Current – Continuous	$T_A = 25^\circ\text{C}$ -4.9	A
$I_{DM}$	Maximum Drain Current – Pulsed	-30	

\* Surface Mounted on FR4 Board,  $t \leq 10$  sec.

ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

**Absolute Maximum Ratings (Cont.)** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Rating	Unit
$P_D$	Maximum Power Dissipation	$T_A = 25^\circ\text{C}$	2.5
		$T_A = 100^\circ\text{C}$	1.0
$T_J$	Maximum Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	
$R_{\theta JA}^*$	Thermal Resistance - Junction to Ambient	50	$^\circ\text{C}/\text{W}$

**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Condition	APM4953			Unit
			Min.	Typ <sup>a</sup> .	Max.	
<b>Static</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_{DS}=-250\mu\text{A}$	-30			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-24\text{V}$ , $V_{GS}=0\text{V}$			-1	$\mu\text{A}$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_{DS}=-250\mu\text{A}$	-1	-1.5	-2	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 25\text{V}$ , $V_{DS}=0\text{V}$			$\pm 100$	nA
$R_{DS(ON)}$	Drain-Source On-state Resistance <sup>b</sup>	$V_{GS}=-10\text{V}$ , $I_{DS}=-4.9\text{A}$		53	60	m $\Omega$
		$V_{GS}=-4.5\text{V}$ , $I_{DS}=-3.6\text{A}$		80	95	
$V_{SD}$	Diode Forward Voltage <sup>b</sup>	$I_{SD}=-1.7\text{A}$ , $V_{GS}=0\text{V}$		-0.7	-1.3	V
<b>Dynamic<sup>a</sup></b>						
$Q_g$	Total Gate Charge	$V_{DS}=-15\text{V}$ , $I_{GS}=-10\text{V}$ $I_D=-4.6\text{A}$		22.3	29	nC
$Q_{gs}$	Gate-Source Charge			4.65		
$Q_{gd}$	Gate-Drain Charge			2		
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=-15\text{V}$ , $I_D=-2\text{A}$ , $V_{GEN}=-10\text{V}$ , $R_G=6\Omega$ $R_L=7.5\Omega$		10	18	ns
$T_r$	Turn-on Rise Time			15	20	
$t_{d(OFF)}$	Turn-off Delay Time			22	38	
$T_f$	Turn-off Fall Time			15	25	
$C_{iss}$	Input Capacitance	$V_{GS}=0\text{V}$		1260		pF
$C_{oss}$	Output Capacitance	$V_{DS}=-25\text{V}$		340		
$C_{rss}$	Reverse Transfer Capacitance	Frequency=1.0MHz		220		

**Notes**

- <sup>a</sup> : Pulse test ; pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
- <sup>b</sup> : Guaranteed by design, not subject to production testing